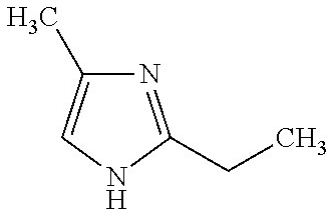
Technical Data

# Resicure™ EMI-24 and EMI-24LV

## Description:

EMI-24 is commonly used as a sole curing agent or as a dicy and anhydride cure accelerator in epoxy resin-based formulations. Typical loading level as a sole curing agent is about 1-5 phr and as a dicy and anhydride cure accelerator is about 0.5 – 3.0 phr.

Resicure EMI-24 LV is a lower viscosity version of Resicure EMI-24.




**2-ethyl-4-methylimidazole**

## Advantages:

- Rapid reactivity at temperature <100°C with 9-12 hours latency
- High glass transition temperature
- High chemical resistance

## Typical Applications:

- One-component adhesives for electronics applications
- Composites such as prepregs and filament winding
- Electrical potting and encapsulation

## Handling Precautions:

Refer to the product Safety Data Sheet

| Typical Properties: | EMI-24 | EMI-24 LV |
|---|---|---|
| Appearance: | Brownish Liquid | |
| Viscosity (@25°C): | 9600 cPs | 1000 cPs |
| Gardner color: | 16 | 15 |
| Moisture content: | <0.4% | < 0.4% |
| Assay: | > 85% | >83% |

| | |
|---|---|
| Recommended use level with Epoxy resin (EEW=190): | 1-5 PHR |

## Typical Performance:

| | |
|---|---|
| Gel time @ 100°C: | 7.0 minutes |
| Gel time @ 150°C: | 1.0 minutes |
| Latency at 25°C: | 9-12 hours |
| HDT: | 163°C |

**ACCI Specialty Materials**

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